



Product Change Notification: MFOL-03MQJR414

Date:

18-Oct-2025

Product Category:

Special Purpose Analog to Digital Converters

Notification Subject:

CCB 7375 Final Notice: Qualification of MMT as a new assembly site for TC7126CKW, TC7126ACKW, TC7126CKW713 and TC7126ACKW713 catalog part numbers (CPN) and QMI519 as a new die attach material for TC7106, TC7106A, TC7107, TC7107A, TC7109, TC7109A, TC7116, TC7116A, TC7117, TC7117A, TC7126, TC7126A and TC7129 device families available in 44L MQFP (10x10x2mm) package.

Affected CPNs:

[MFOL-03MQJR414_Affected_CPN_10182025.pdf](#)

[MFOL-03MQJR414_Affected_CPN_10182025.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MMT as a new assembly site for TC7126CKW, TC7126ACKW, TC7126CKW713 and TC7126ACKW713 catalog part numbers (CPN) and QMI519 as a new die attach material for TC7106, TC7106A, TC7107, TC7107A, TC7109, TC7109A, TC7116, TC7116A, TC7117, TC7117A, TC7126, TC7126A and TC7129 device families available in 44L MQFP (10x10x2mm) package.

Pre and Post Summary Changes:

** Applies only for TC7126CKW, TC7126ACKW, TC7126CKW713 and TC7126ACKW713 catalog part numbers.*

	Pre Change	Post Change
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Assembly Site	Amkor Technology Philippine (P1/P2), INC. (ANAP)	Amkor Technology Philippine (P1/P2), INC. (ANAP)	Microchip Technology Thailand (Branch) (MMT)
Wire Material	Au	Au	Au
Die Attach Material	3230 (PFAS)	3230 (PFAS)	QMI519 (PFAS-free)
Molding Compound Material	G700M	G700M	G600V
Lead-Frame Material	C7025	C7025	C7025
Lead-Frame Paddle Size	244x244 mils	244x244 mils	275x275 mils
DAP Surface Prep	Ag Spot Plated	Ag Spot Plated	Bare Cu
Lead- Frame Design	See pre and post change for comparison.		

** Applies for remaining affected CPNs*

	Pre Change		Post Change	
Assembly Site	Amkor Technology Philippine (P1/P2), INC. (ANAP)	Microchip Technology Thailand (Branch) (MMT)	Amkor Technology Philippine (P1/P2), INC. (ANAP)	Microchip Technology Thailand (Branch) (MMT)
Wire Material	Au	Au	Au	Au
Die Attach Material	3230 (PFAS)	3280 (PFAS)	3230 (PFAS)	QMI519 (PFAS-free)
Molding Compound Material	G700M	G600V	G700M	G600V
Lead-Frame Material	C7025	C7025	C7025	C7025
DAP Surface Prep	Ag Spot Plated	Ag Spot Plated	Ag Spot Plated	Bare Cu
Lead- Frame Design	See pre and post change for comparison.			

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance and manufacturability by qualifying MMT as a new assembly site and QMI519 as a new die attach material.

Change Implementation Status: In Progress

Estimated First Ship Date: 10 November 2025 (date code: 2546)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	March 2025					>	October 2025					November 2025			
Work Week	10	11	12	13	14		40	41	42	43	44	45	46	47	48
Initial PCN Issue Date		x													
Qual Report Availability									x						
Final PCN Issue Date									x						
Estimated Implementation Date													x		

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: March 10, 2025: Issued final notification.

March 17, 2025: Re-issued the PCN notification to update the revision history stating from final notification to initial notification.

October 18, 2025: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on November 10, 2025. Updated the reason for change to include QM519 die attach material and included in Pre and Post change table that QMI519 is a PFAS-free material. Attached the PFAS Elimination and Die Attach Elimination file.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance

regarding the material content of the applicable product.

Attachments:

PCN_MFOL-03MQJR414_Pre and Post Change_Summary.pdf

PCN_MFOL-03MQJR414 Qual Report.pdf

PFAS Elimination and Die Attach_Explanation.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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